

Integr8tor v9.1

Ucamco CONFIDENTIAL

Integrotor Version 9.1







We are pleased to announce the release of Integr8tor version 9.1

Integr8tor v9.1 offers significant improvements and new functionality, explained in these release notes. It also offers better quality and a number of bug fixes.

We recommend that you install version 9.1 as soon as possible.



Release history

Commitment to regular updates



Ucamco

Overview

New Functionality and Enhancements

- Support for Gerber X₂ datasets.
- Second generation edge-connector recognition.
- New optimized minimum line width detection algorithm.
- Additional BGA characteristics reported.
- Minimum negative soldermask ring reported.
- Better and faster layer stackup recognition.
- 'Secondary' format support for single job archives with multiple formats.
- More archive extensions are supported



Support for Gerber X2 datasets

All features from the new Gerber version are fully supported by Integr8tor v9.1

- Datasets are processed much faster compared to Gerber version 1.
- Full, reliable and automatic detection of layer stackup
- More accurate and faster QED values such as:
 - ViaDrill/ComponentDrill/MechanicalDrill/Slot/...
 - Viapad/componentpad
 - SMDpad/BGApad/Fiducial/...
 - Conductors for Impedance
 - Profile/CutOut

The benefits of X₂ are clear: faster, more automatic, more accurate



Support for Gerber X2 datasets

gbr x2

| INITIAL | RENAMED | FORMAT | FUNCTION | POSITION |
|--|------------|--------|-------------|----------|
| Gerber_PCB_DataExample_2_Legend_Top.gbr | Gerber_PCB | gerx2 | legend | top |
| Gerber_PCB_DataExample_2_Soldermask_Top.gbr | Gerber_PCB | gerx2 | soldermask | top |
| Gerber_PCB_DataExample_2_Copper_L1_Top.gbr | Gerber_PCB | gerx2 | outer | 1 |
| Gerber_PCB_DataExample_2_Copper_L2_Inr.gbr | Gerber_PCB | gerx2 | inner | 2 |
| Gerber_PCB_DataExample_2_Copper_L3_Inr.gbr | Gerber_PCB | gerx2 | inner | 3 |
| Gerber_PCB_DataExample_2_Copper_L4_Inr.gbr | Gerber_PCB | gerx2 | inner | 4 |
| Gerber_PCB_DataExample_2_Copper_L5_Inr.gbr | Gerber_PCB | gerx2 | inner | 5 |
| Gerber_PCB_DataExample_2_Copper_L6_Inr.gbr | Gerber_PCB | gerx2 | inner | 6 |
| Gerber_PCB_DataExample_2_Copper_L7_Inr.gbr | Gerber_PCB | gerx2 | inner | 7 |
| Gerber_PCB_DataExample_2_Copper_L8_Inr.gbr | Gerber_PCB | gerx2 | inner | 8 |
| Gerber_PCB_DataExample_2_Copper_L9_Inr.gbr | Gerber_PCB | gerx2 | inner | 9 |
| Gerber_PCB_DataExample_2_Copper_L10_Bot.gbr | Gerber_PCB | gerx2 | outer | 10 |
| Gerber_PCB_DataExample_2_Soldermask_Bot.gbr | Gerber_PCB | gerx2 | soldermask | bottom |
| Gerber_PCB_DataExample_2_Legend_Bot.gbr | Gerber_PCB | gerx2 | legend | bottom |
| Gerber_PCB_DataExample_2_NonPlated_1_10_NPTH_Drill.gbr | Gerber_PCB | gerx2 | unplated | 1-10 |
| Gerber_PCB_DataExample_2_Plated_1_10_PTH_Drill.gbr | Gerber_PCB | gerx2 | plated | 1-10 |
| Gerber_PCB_DataExample_2_Plated_1_2_Blind_Drill.gbr | Gerber_PCB | gerx2 | plated | 1-2 |
| Gerber_PCB_DataExample_2_Plated_2_9_Buried_Drill.gbr | Gerber_PCB | gerx2 | plated | 2-9 |
| Gerber_PCB_DataExample_2_Plated_9_10_Burried_Drill.gbr | Gerber_PCB | gerx2 | plated | 9-10 |
| Gerber_PCB_DataExample_2_Profile_NP.gbr | Gerber_PCB | gerx2 | cad_outline | none |



Second generation edge-connector recognition.

Based on feedback from our customers, we develop a new edge connector recognition module.

More variants are now detected which results in an even more accurate QED report:

• Connectors with irregular fingers:



• Connectors from which the fingers are complex pads:





New optimized minimum line width detection algorithm.

The minimum line width detection could take a long time on heavy jobs.

A complete new algorithm gives a big performance boost on these jobs. Processing times can be reduced by more than 30% depending on the data.

Improved minimum line width detection on curved or cornered data.

Not only has the performance been improved but also in some cases involving copper planes, the accuracy is now higher.

The 2 improvements result in a faster and more accurate minimum line width.







Additional BGA characteristics reported.

The SMD section has been extended with several new BGA related characteristics.

Features

BGA Min. Pitch

Show the Minimum pitch distance between 2 BGA pads.

BGA Drilled

Indicates if BGA pads are drilled or not.

Benefits

• Gives more in depth information about BGA usage and characteristics.

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| SMD | | | | | | |
|--------|--------------|----------------|----------|-------------------------------|----------------|-------------|
| Side | Pads (Total) | Excl. BGA Pads | BGA Pads | All Tracks in BGA Centered | BGA Min. Pitch | BGA Drilled |
| Тор | 710 | 317 | 393 | Yes | 1.000 | Yes |
| Bottom | 695 | 551 | 144 | Yes | 0.800 | Yes |
| All | 1405 | 868 | 537 | Yes | 0.800 | Yes |



» We try harder «

Minimum negative soldermask ring.

The Solder mask section has been extended with a new characteristic.

- In addition to the ring provided for "Non Solder Mask Defined" pads (Positive ring), the ring for "Solder Mask Defined" pads is provided
- For "Solder Mask Defined" (SMD) copper pads where solder mask is on the land of the copper pad, the ring value (or negative ring) of mask on the pad is given.
- Provides earlier detection of issues with "Solder mask defined" BGA and QFP components



Solder Mask

| Side | Min. Positive Ring | Min. Negative Ring | Min. Clr. Mask to Mask | Min. Web | Min. Clr. Mask to Copper |
|--------|--------------------|--------------------|---------------------------|----------|-----------------------------|
| | mm | mm | mm | mm | mm |
| Тор | 0.000 | 0.038 | 0.094 | 0.179 | 0.022 |
| Bottom | 0.008 | 0.038 | 0.109 | 0.109 | 0.007 |



Other important improvements

Better and faster layer stackup recognition

- Our stackup rule database has been extended with a considerable amount of new rules.
- The speed has been drastically improved.

'Secondary' format support for single job archives with multiple formats

Sometimes mechanical drawings are provided in different formats other than layer images.

Where we already supported 'secondary' Gerber image conversion in the case of 'primary' DPF or ODB, we now also support the opposite. i.e. converting secondary DPF or ODB files in case the archive comes in primary Gerber format. The converted files being added as extra drawing layers in the job.

A new preference selects whether to have the extra Gerber drawings included with an original DPF job export or not.

More archive extensions are supported

- Added .taz as supported archive file extension.
- Integr8tor can now deal with extension-less archive names.

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